

SOT1921-4(D)

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 2.2 mm body

13 August 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN24
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-07-2019
Manufacturer package code	98ASA01455D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
package height	-	2.2	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	24	-	



HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 2.2 mm body

2 Package outline

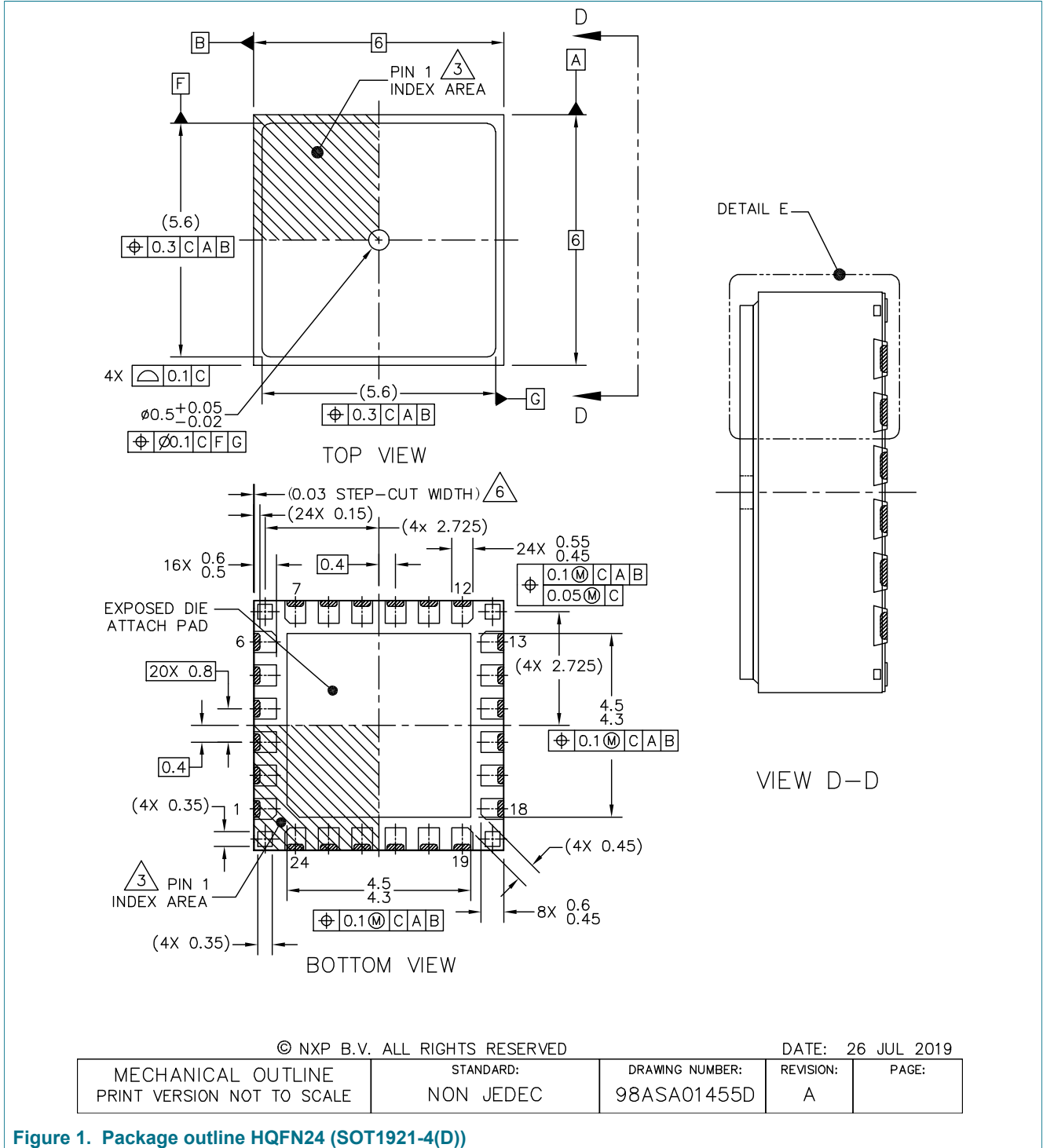


Figure 1. Package outline HQFN24 (SOT1921-4(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 2.2 mm body

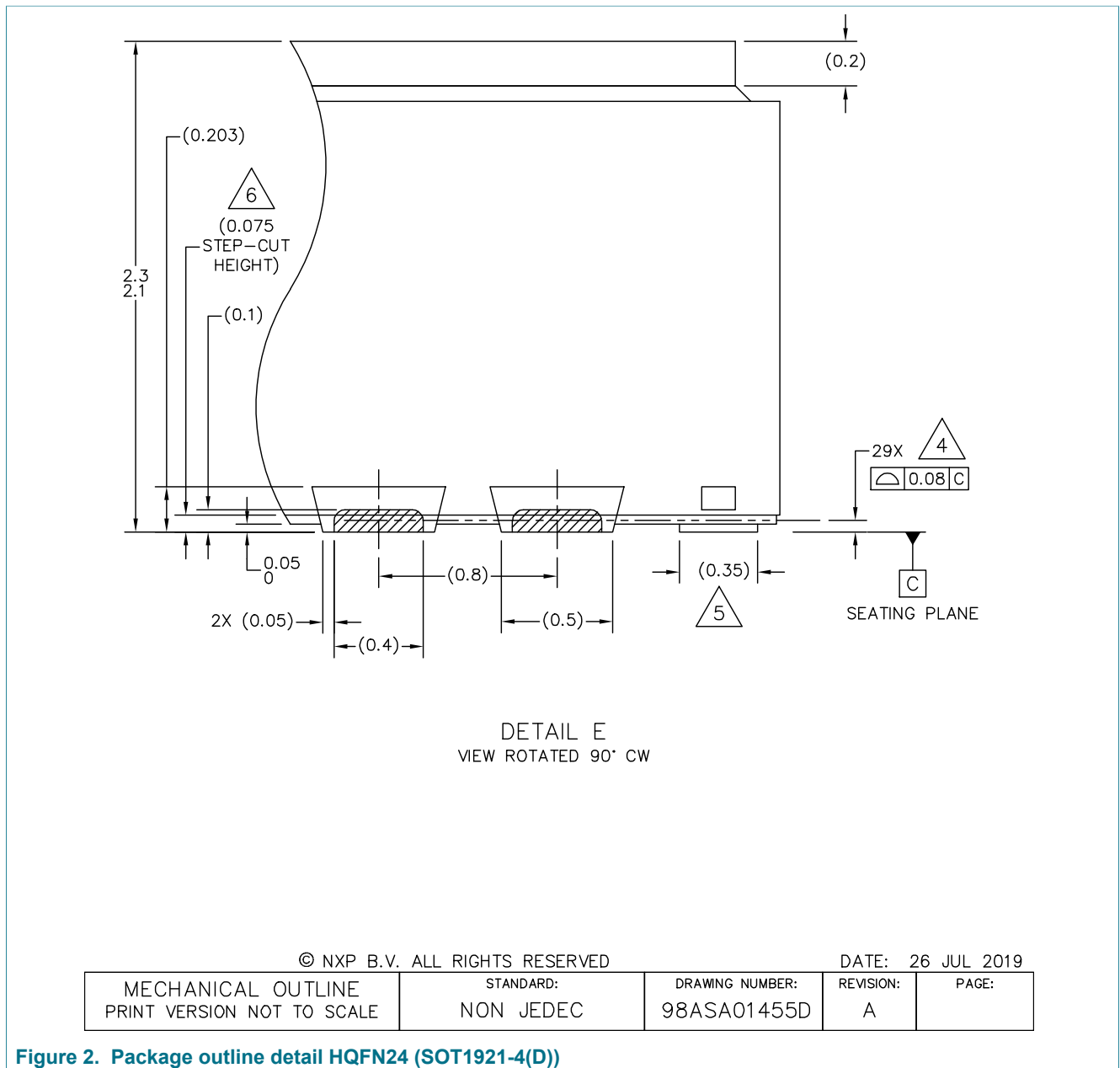


Figure 2. Package outline detail HQFN24 (SOT1921-4(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 2.2 mm body

3 Soldering

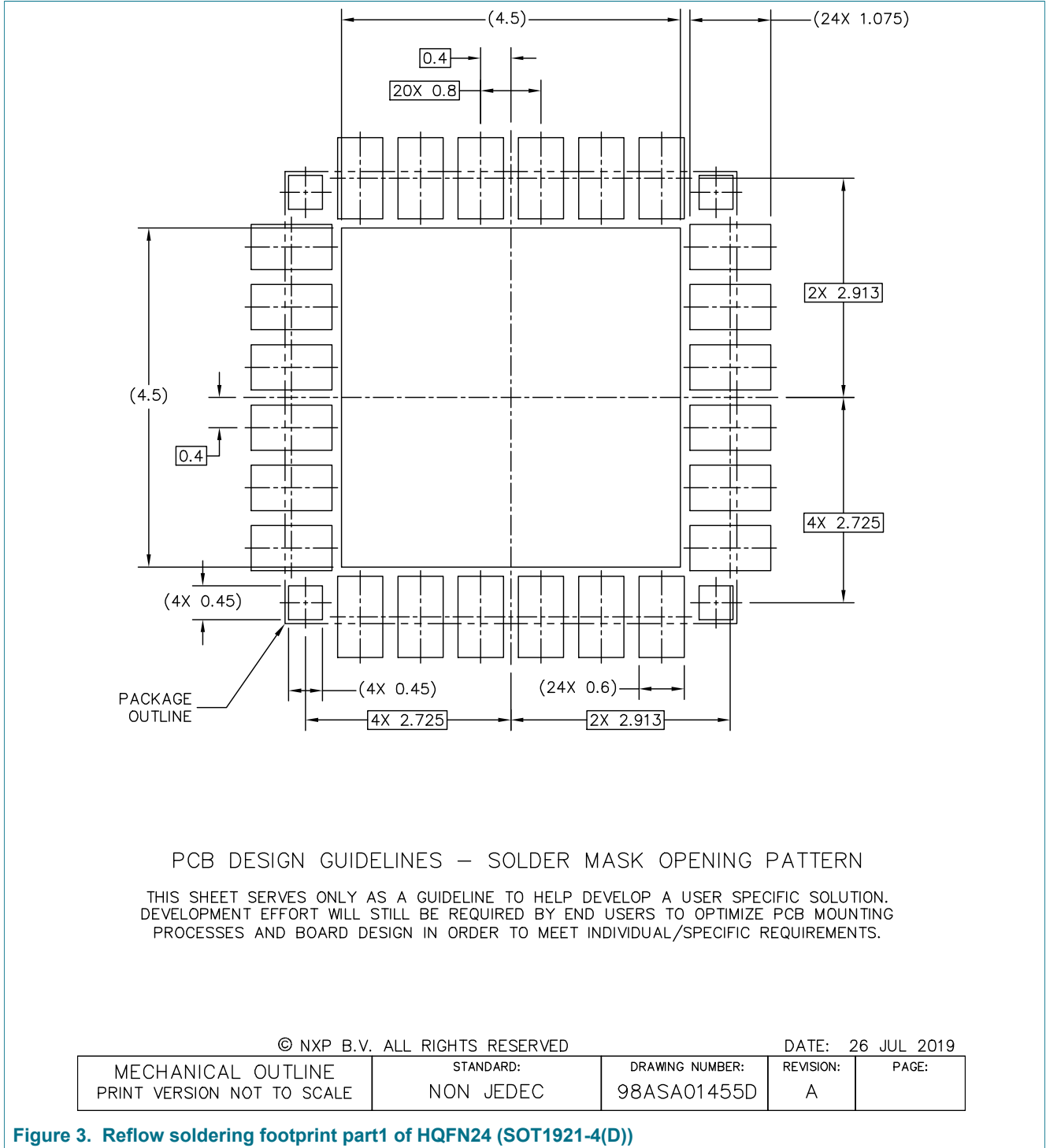
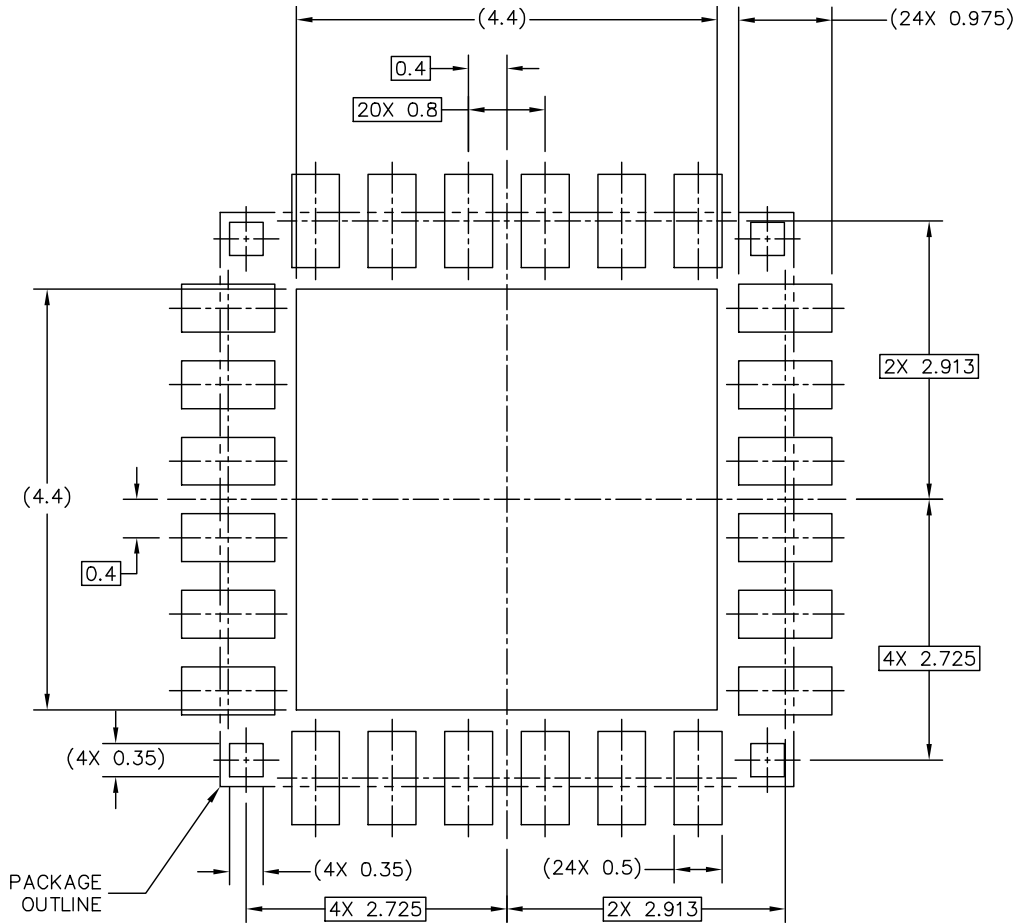


Figure 3. Reflow soldering footprint part1 of HQFN24 (SOT1921-4(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 2.2 mm body



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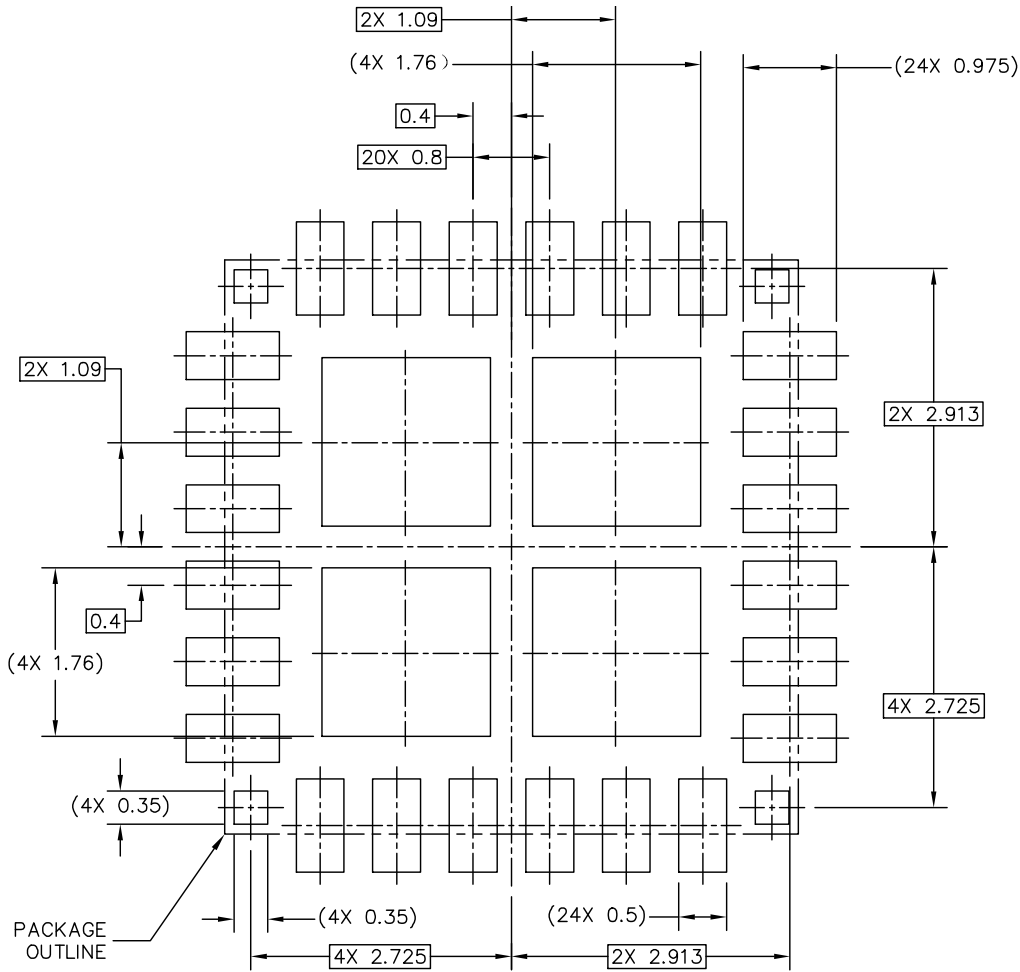
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Figure 4. Reflow soldering footprint part2 of HQFN24 (SOT1921-4(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 2.2 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 of HQFN24 (SOT1921-4(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 2.2 mm body

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
- 5. ANCHORING PADS.
- 6. STEP-CUT IS APPLIED FOR BURR REMOVAL ONLY.

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Figure 6. Package outline note HQFN24 (SOT1921-4(D))

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Contents

1 Package summary1
2 Package outline2
3 Soldering4
4 Legal information8